Product Summary

Device	BV_{DSS}	$R_{DS(ON)}$ Max	I_D Max T_A = +25°C
Q1	30V	1.5Ω @ V_{GS} = 4.5V	0.40A
		2.0Ω @ V_{GS} = 2.5V	0.35A
		3.0Ω @ V_{GS} = 1.8V	0.28A
		4.5Ω @ V_{GS} = 1.5V	0.23A
Q2	-30V	5Ω @ V_{GS} = -4.5V	-0.22A
		6Ω @ V_{GS} = -2.5V	-0.20A
		7Ω @ V_{GS} = -1.8V	-0.18A
		10Ω @ V_{GS} = -1.5V	-0.15A

Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package 0.8mm x 0.6mm
- **ESD Protected Gate**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **The DMC31D5UDAQ is suitable for automotive applications requiring specific change control; This part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**
  https://www.diodes.com/quality/product-definitions/

Description and Applications

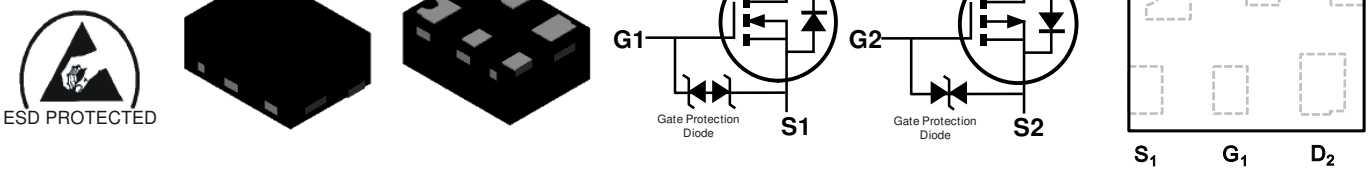
This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch

Mechanical Data

- Case: X2-DFN0806-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.027 grams (Approximate)

X2-DFN0806-6



Top View | Bottom View | Device Symbol | Pin Configuration Top View

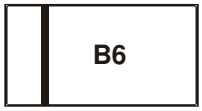
Ordering Information (Note 4)

Part Number	Case	Packaging
DMC31D5UDAQ-7B	X2-DFN0806-6	10,000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

X2-DFN0806-6



Top View

B6 = Product Type Marking Code
Bar Denotes Pin 1

Maximum Ratings Q1 N-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	±12	V
Continuous Drain Current (Note 5) V_{GS} = 4.5V	Steady State	T_A = +25°C	I_D	0.4	A
		T_A = +70°C		0.32	
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	0.8	A
Pulsed Drain Current (Note 6)			I_{DM}	0.8	A

Maximum Ratings Q2 P-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	-30	V
Gate-Source Voltage			V_{GSS}	±12	V
Continuous Drain Current (Note 5) V_{GS} = -4.5V	Steady State	T_A = +25°C	I_D	-0.22	A
		T_A = +70°C		-0.17	
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	-0.8	A
Pulsed Drain Current (Note 6)			I_{DM}	-0.8	A

Thermal Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	0.37	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	345	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics Q1 N-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current @ T_C = +25°C	I_{DSS}	—	—	100	nA	V_{DS} = 24V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±10V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.4	—	1.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	1.2	1.5	Ω	V_{GS} = 4.5V, I_D = 100mA
		—	1.3	2.0		V_{GS} = 2.5V, I_D = 50mA
		—	1.5	3.0		V_{GS} = 1.8V, I_D = 20mA
		—	1.8	4.5		V_{GS} = 1.5V, I_D = 10mA
Diode Forward Voltage	V_{SD}	—	0.6	1.0	V	V_{GS} = 0V, I_S = 10mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	22.6	—	pF	V_{DS} = 15V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	2.68	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	1.8	—	pF	
Total Gate Charge	Q_g	—	0.38	—	nC	V_{GS} = 4.5V, V_{DS} = 15V, I_D = 200mA
Gate-Source Charge	Q_{gs}	—	0.05	—	nC	
Gate-Drain Charge	Q_{gd}	—	0.07	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	3.2	—	ns	V_{DD} = 15V, V_{GS} = 4.5V, R_G = 2Ω, I_D = 200mA
Turn-On Rise Time	t_R	—	2.2	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	21	—	ns	
Turn-Off Fall Time	t_F	—	7.5	—	ns	

Notes: 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
6. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

Electrical Characteristics Q2 P-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-30	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current @ T_C = +25°C	I_{DSS}	—	—	-100	nA	V_{DS} = -24V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±10V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.4	—	-1.0	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	1.8	5	Ω	V_{GS} = -4.5V, I_D = -100mA
		—	2.3	6		V_{GS} = -2.5V, I_D = -50mA
		—	3	7		V_{GS} = -1.8V, I_D = -20mA
		—	3.4	10		V_{GS} = -1.5V, I_D = -10mA
Diode Forward Voltage	V_{SD}	—	-0.6	-1.0	V	V_{GS} = 0V, I_S = -10mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	21.8	—	pF	V_{DS} = -15V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	2.82	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	1.66	—	pF	
Total Gate Charge	Q_g	—	0.35	—	nC	V_{GS} = -4.5V, V_{DS} =- 15V, I_D = -200mA
Gate-Source Charge	Q_{gs}	—	0.05	—	nC	
Gate-Drain Charge	Q_{gd}	—	0.10	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	3.5	—	ns	V_{DD} = -15V, V_{GS} = -4.5V, R_G = 2Ω, I_D = -200mA
Turn-On Rise Time	t_R	—	5.2	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	18.8	—	ns	
Turn-Off Fall Time	t_F	—	8.7	—	ns	

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

Typical Characteristics - N-CHANNEL

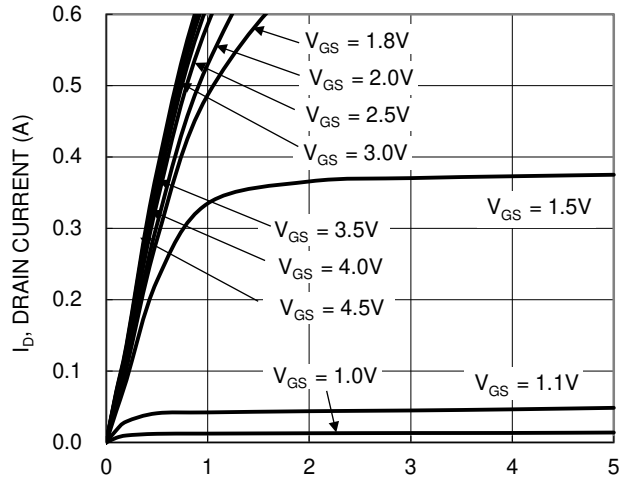


Figure 1. Typical Output Characteristic

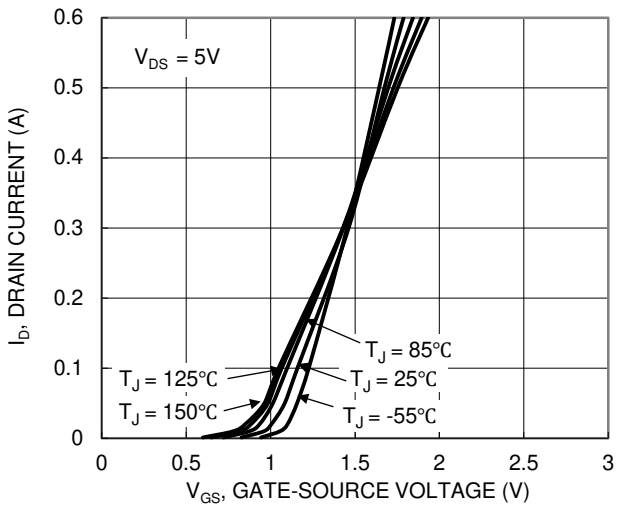


Figure 2. Typical Transfer Characteristic

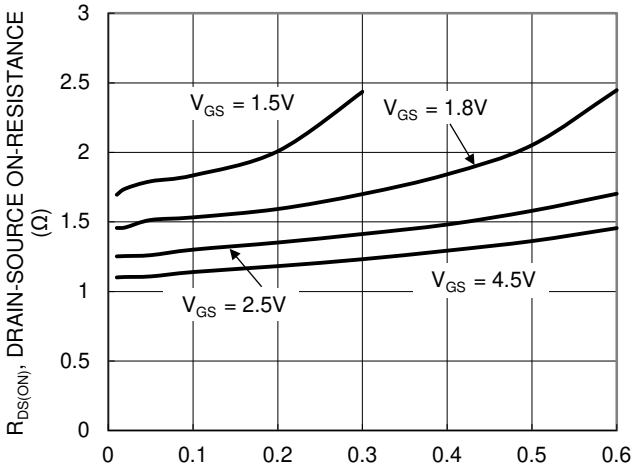


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

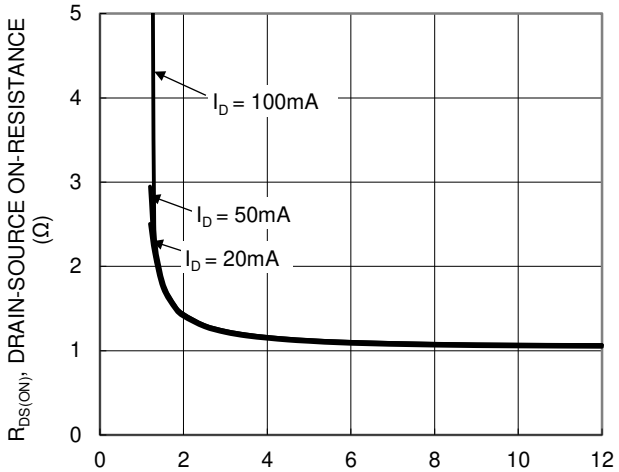


Figure 4. Typical Transfer Characteristic

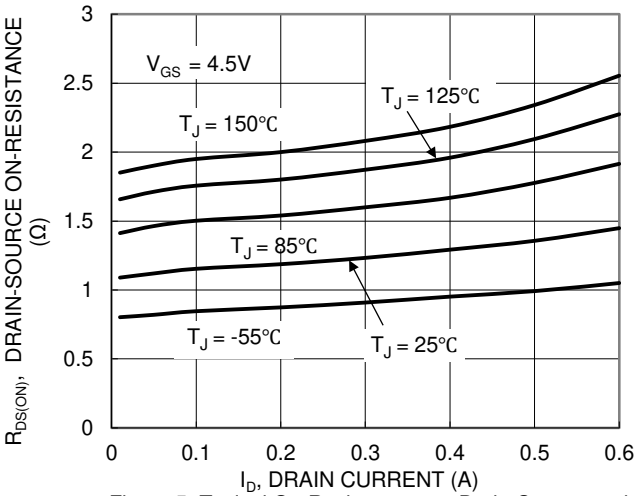


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

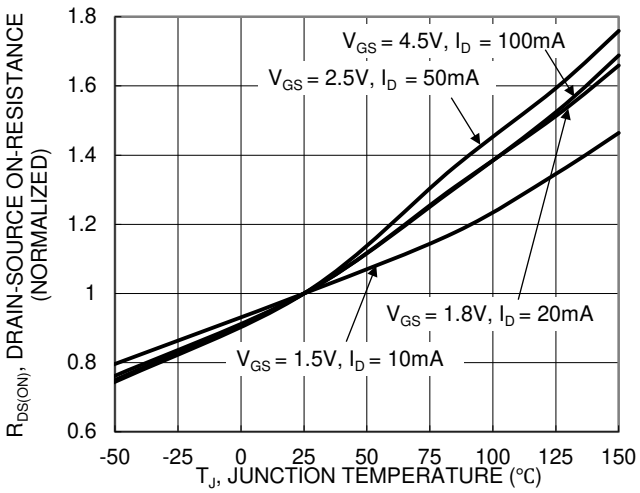


Figure 6. On-Resistance Variation with Temperature

Typical Characteristics - N-CHANNEL (continued)

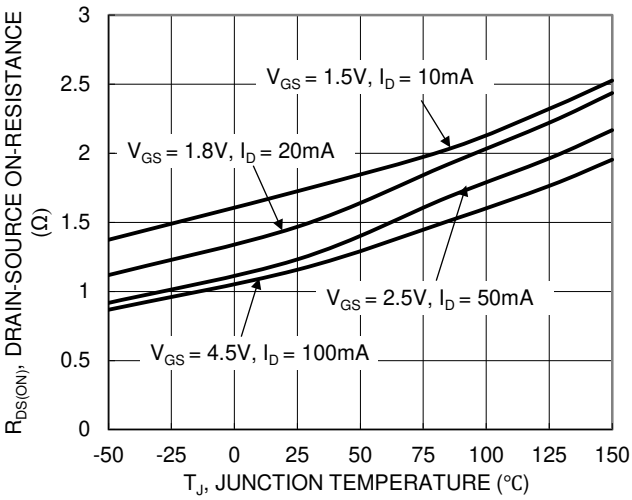


Figure 7. On-Resistance Variation with Temperature

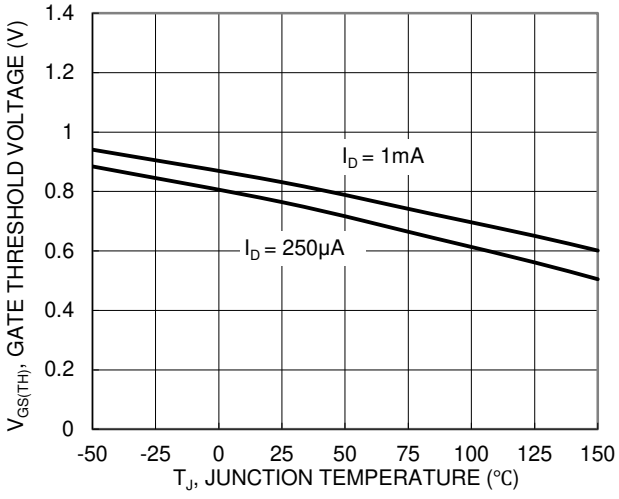


Figure 8. Gate Threshold Variation vs. Junction Temperature

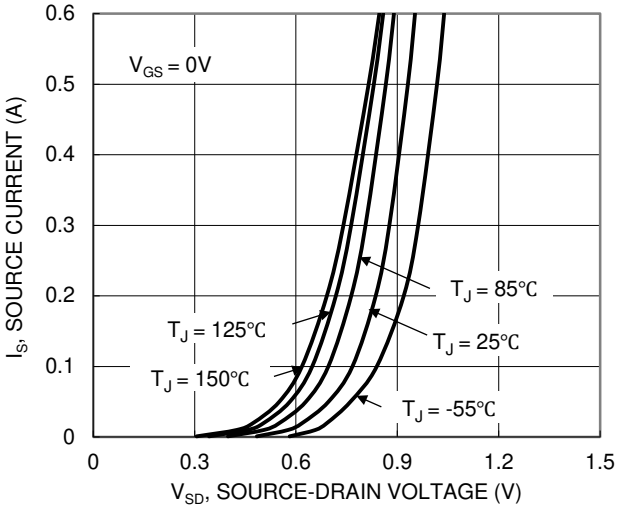


Figure 9. Diode Forward Voltage vs. Current

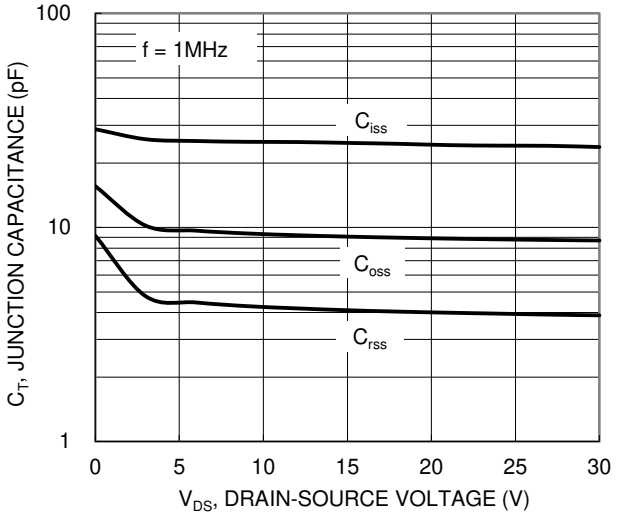


Figure 10. Typical Junction Capacitance

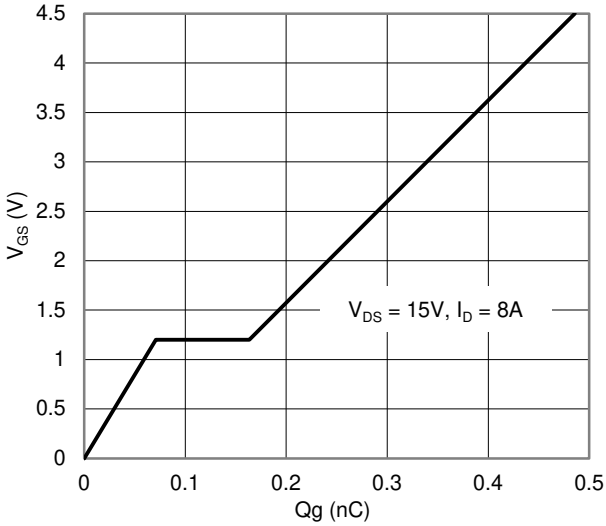


Figure 11. Gate Charge

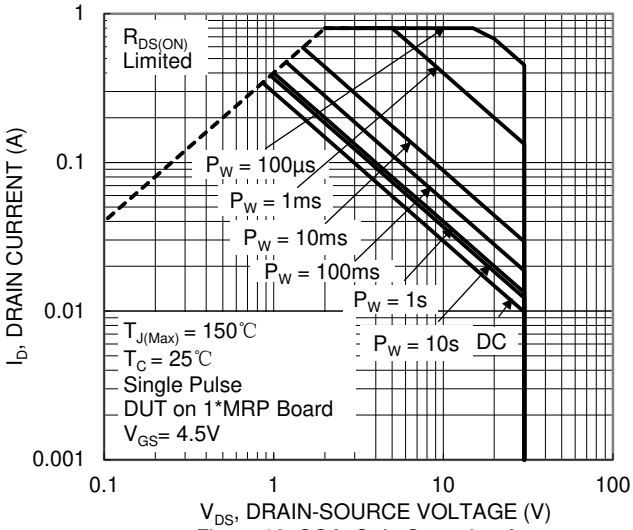


Figure 12. SOA, Safe Operation Area

Typical Characteristics - P-CHANNEL

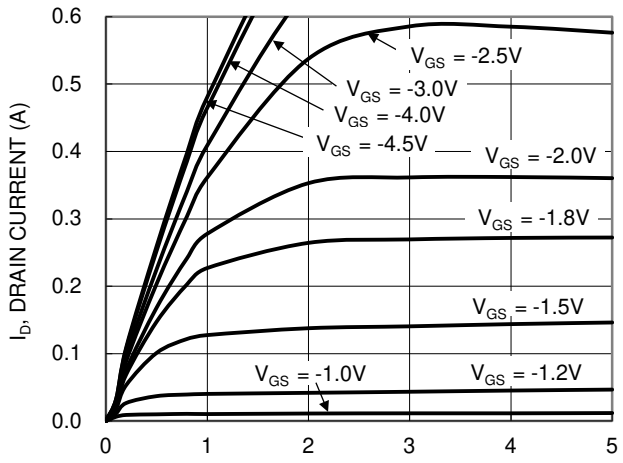


Figure 13. Typical Output Characteristic

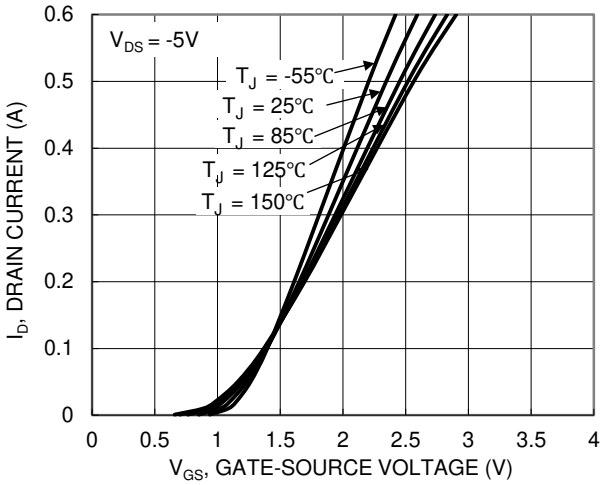


Figure 14. Typical Transfer Characteristic

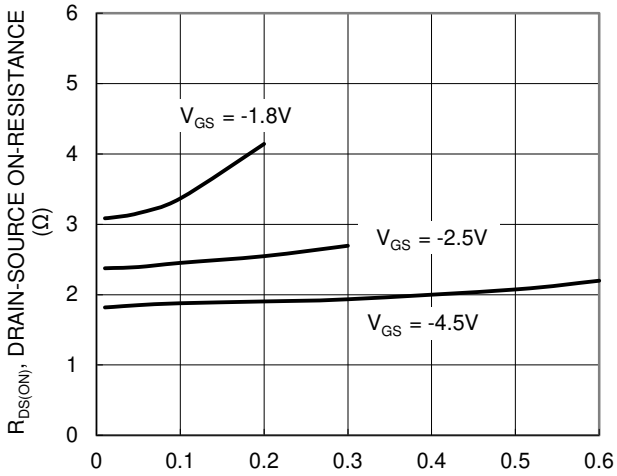


Figure 15. Typical On-Resistance vs. Drain Current and Gate Voltage

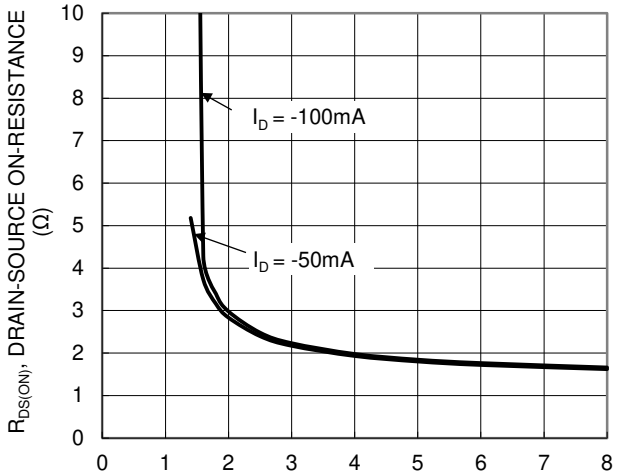


Figure 16. Typical Transfer Characteristic

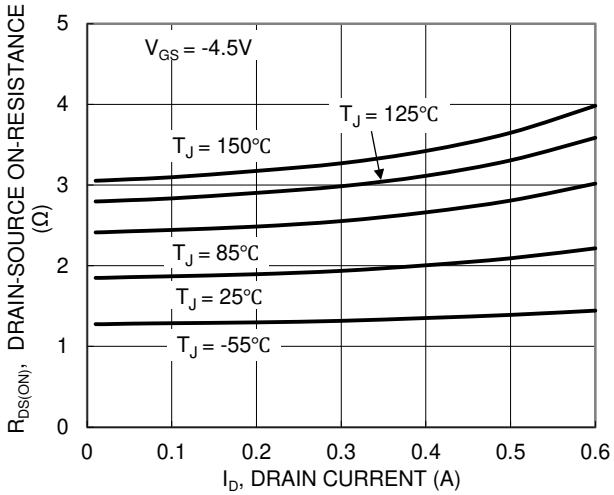


Figure 17. Typical On-Resistance vs. Drain Current and Junction Temperature

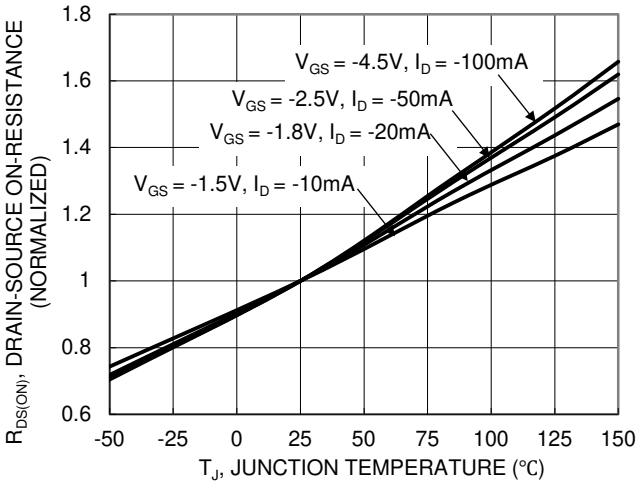


Figure 18. On-Resistance Variation with Junction Temperature

Typical Characteristics - P-CHANNEL (continued)

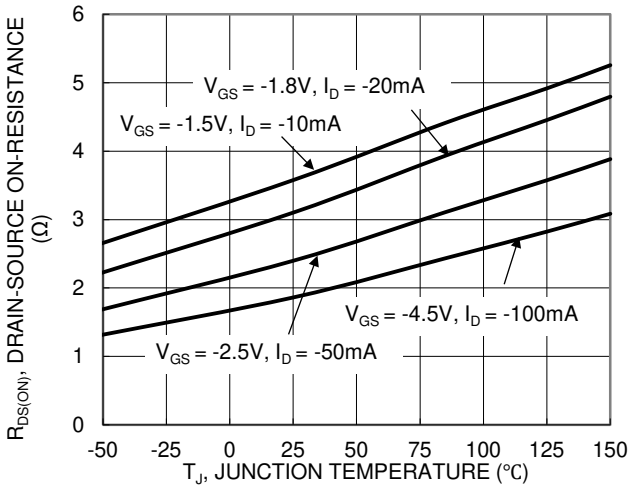


Figure 19. On-Resistance Variation with Junction Temperature

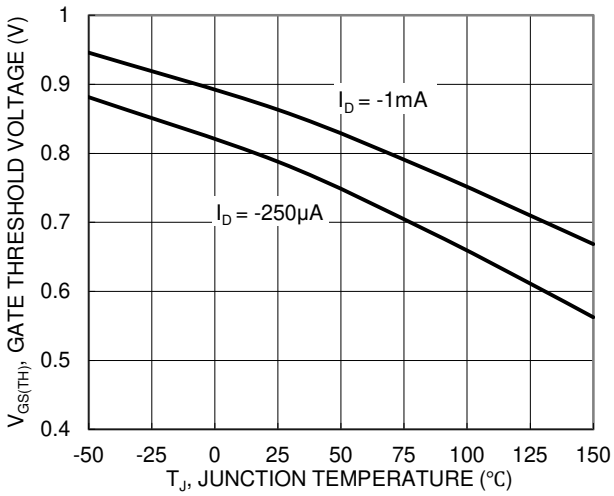


Figure 20. Gate Threshold Variation vs. Junction Temperature

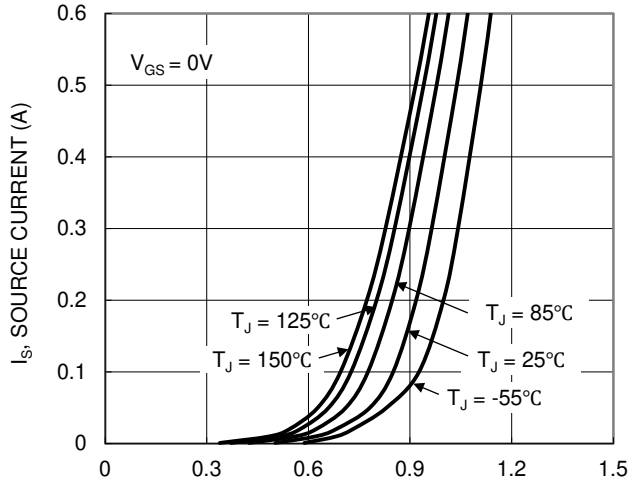


Figure 21. Diode Forward Voltage vs. Current

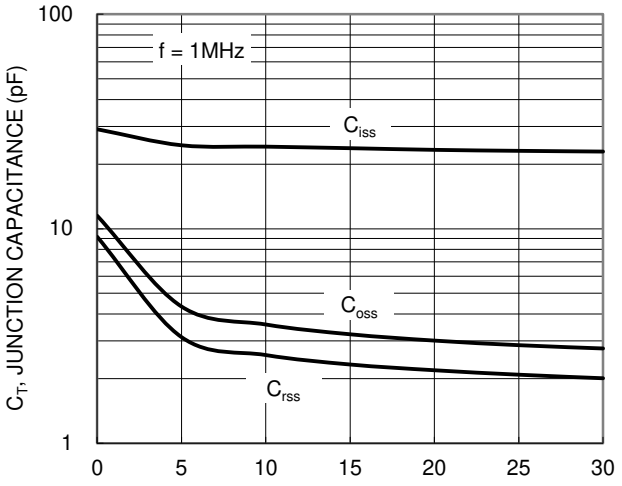


Figure 22. Typical Junction Capacitance

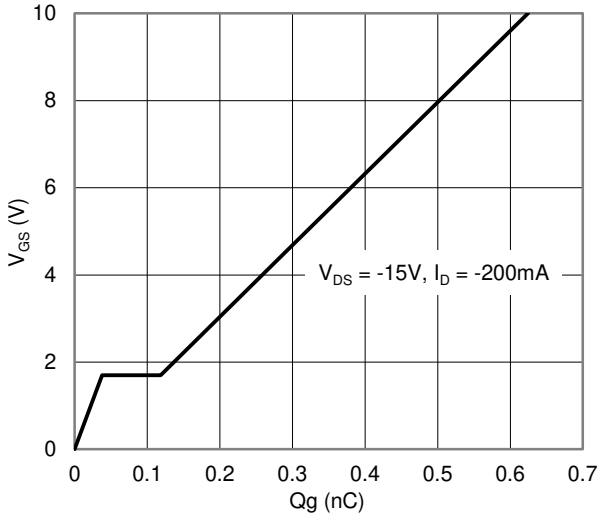


Figure 23. Gate Charge

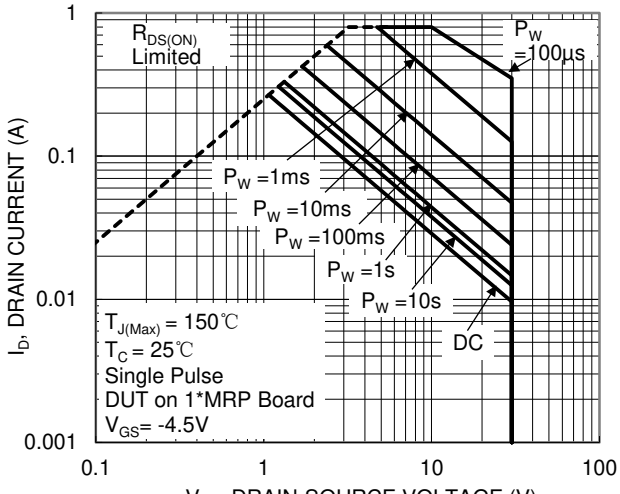


Figure 24. SOA, Safe Operation Area

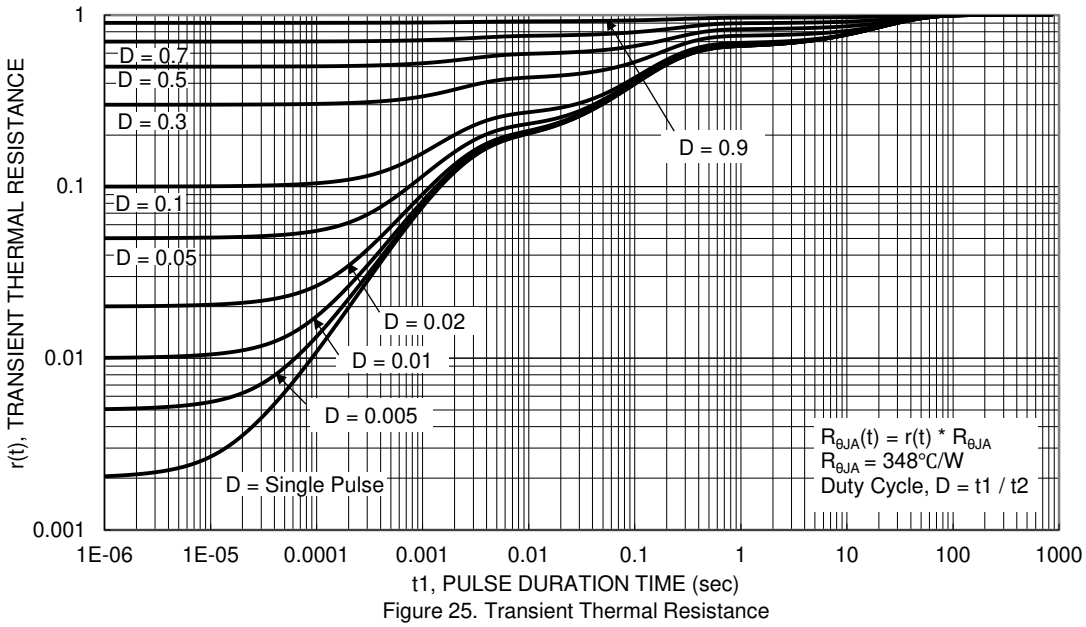
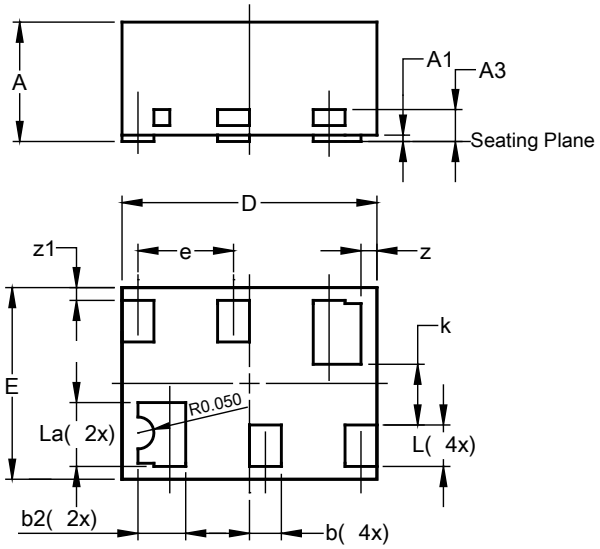


Figure 25. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN0806-6

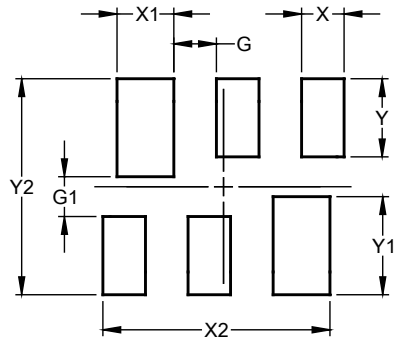


X2-DFN0806-6			
Dim	**Min**	**Max**	**Typ**
A	--	0.40	0.36
A1	0.00	0.03	0.02
A3	--	--	0.10
b	0.07	0.15	0.10
b2	0.10	0.20	0.15
D	0.75	0.85	0.80
E	0.55	0.65	0.60
e	--	--	0.30
k	--	--	0.19
L	0.10	0.18	0.13
La	0.17	0.25	0.20
z	--	--	0.05
z1	--	--	0.04
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN0806-6



Dimensions	Value (in mm)
G	0.150
G1	0.140
X	0.150
X1	0.200
X2	0.800
Y	0.275
Y1	0.345
Y2	0.760

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A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

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